

BFP450

Surface mount high linearity wideband silicon NPN RF bipolar transistor



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Technical documents



Simulation



Support

Product description

The BFP450 is a low noise device based on a grounded emitter (SIEGET™) that is part of Infineon's established fourth generation RF bipolar transistor family. Its transition frequency f_T of 24 GHz, collector design and high linearity characteristics make the device suitable for energy efficiency applications up to 3 GHz. It remains cost competitive without compromising on ease of use.



Feature list

- Minimum noise figure $NF_{min} = 1.7$ dB at 1.9 GHz, 3 V, 50 mA
- High gain $G_{ma} = 15.5$ dB at 1.9 GHz, 3 V, 90 mA
- $OIP_3 = 31$ dBm at 1.9 GHz, 3 V, 90 mA

Product validation

Qualified for industrial applications according to the relevant tests of JEDEC47/20/22.

Potential applications

- Broadband amplifiers
- Low noise, high linearity amplifiers for sub-1 GHz ISM band applications

Device information

Table 1 Part information

Product name / Ordering code	Package	Pin configuration				Marking	Pieces / Reel
BFP450 / BFP450H6327XTSA1	SOT343	1 = B	2 = E	3 = C	4 = E	ANs	3000
BFP450 / BFP450H6433XTMA1							10000

Attention: ESD (Electrostatic discharge) sensitive device, observe handling precautions

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Absolute maximum ratings

1 Absolute maximum ratings

Table 2 Absolute maximum ratings at $T_A = 25\text{ °C}$ (unless otherwise specified)

Parameter	Symbol	Values		Unit	Note or test condition
		Min.	Max.		
Collector emitter voltage	V_{CEO}	-	4.5	V	Open base
			4.1		$T_A = -55\text{ °C}$, open base
Collector emitter voltage	V_{CES}		15		E-B short circuited
Collector base voltage	V_{CBO}		15		Open emitter
Emitter base voltage	V_{EBO}		1.5		Open collector
Base current	I_B		10	mA	-
Collector current	I_C		170		
Total power dissipation ¹⁾	P_{tot}		500	mW	$T_S \leq 90\text{ °C}$
Junction temperature	T_J		150	°C	-
Storage temperature	T_{Stg}	-55			

Attention: *Stresses above the max. values listed here may cause permanent damage to the device. Exposure to absolute maximum rating conditions for extended periods may affect device reliability. Exceeding only one of these values may cause irreversible damage to the integrated circuit.*

¹ T_S is the soldering point temperature. T_S is measured on the emitter lead at the soldering point of the PCB.

Thermal characteristics

2 Thermal characteristics

Table 3 Thermal resistance

Parameter	Symbol	Values			Unit	Note or test condition
		Min.	Typ.	Max.		
Junction - soldering point	R_{thJS}	-	120	-	K/W	-

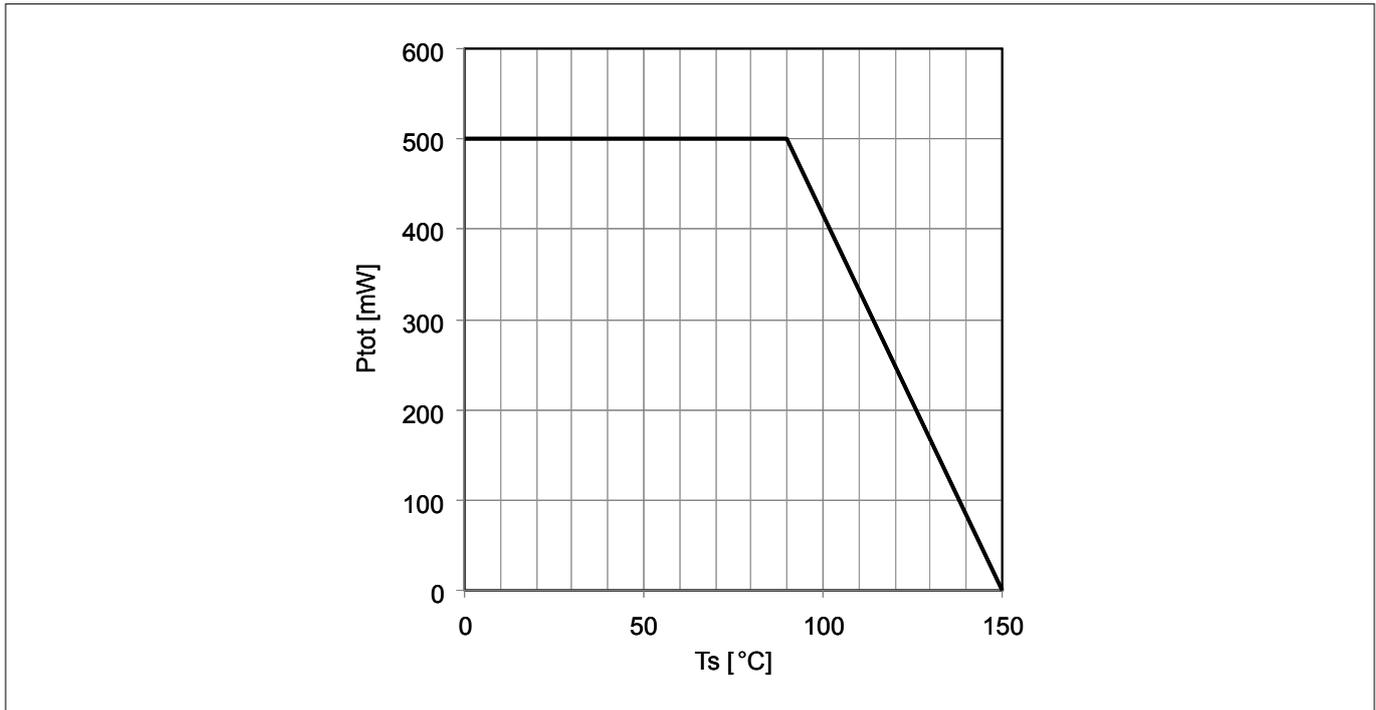


Figure 1 Total power dissipation $P_{tot} = f(T_s)$

Electrical characteristics

3 Electrical characteristics

3.1 DC characteristics

Table 4 DC characteristics at $T_A = 25\text{ °C}$

Parameter	Symbol	Values			Unit	Note or test condition
		Min.	Typ.	Max.		
Collector emitter breakdown voltage	$V_{(BR)CEO}$	4.5	5	–	V	$I_C = 1\text{ mA}$, $I_B = 0$, open base
Collector emitter leakage current	I_{CES}	–	–	1 ²⁾ 30 ²⁾	μA nA	$V_{CE} = 15\text{ V}$, $V_{BE} = 0$, $V_{CE} = 3\text{ V}$, $V_{BE} = 0$, E-B short circuited
Collector base leakage current	I_{CBO}		1	30 ²⁾	nA	$V_{CB} = 3\text{ V}$, $I_E = 0$, open emitter
Emitter base leakage current	I_{EBO}		0.05	3 ²⁾	μA	$V_{EB} = 0.5\text{ V}$, $I_C = 0$, open collector
DC current gain	h_{FE}	60 50	95 85	130 120		$V_{CE} = 4\text{ V}$, $I_C = 50\text{ mA}$, $V_{CE} = 3\text{ V}$, $I_C = 90\text{ mA}$, pulse measured

3.2 General AC characteristics

Table 5 General AC characteristics at $T_A = 25\text{ °C}$

Parameter	Symbol	Values			Unit	Note or test condition
		Min.	Typ.	Max.		
Transition frequency	f_T	18	24	–	GHz	$V_{CE} = 3\text{ V}$, $I_C = 90\text{ mA}$, $f = 1\text{ GHz}$
Collector base capacitance	C_{CB}	–	0.48	0.8	pF	$V_{CB} = 3\text{ V}$, $V_{BE} = 0$, $f = 1\text{ MHz}$, emitter grounded
Collector emitter capacitance	C_{CE}		1.2	–		$V_{CE} = 3\text{ V}$, $V_{BE} = 0$, $f = 1\text{ MHz}$, base grounded
Emitter base capacitance	C_{EB}		1.7			$V_{EB} = 0.5\text{ V}$, $V_{CB} = 0$, $f = 1\text{ MHz}$, collector grounded

²⁾ Maximum values not limited by the device but by the short cycle time of the 100% test.

Electrical characteristics

3.3 Frequency dependent AC characteristics

Measurement setup is a test fixture with Bias-T's in a 50 Ω system, $T_A = 25\text{ °C}$.

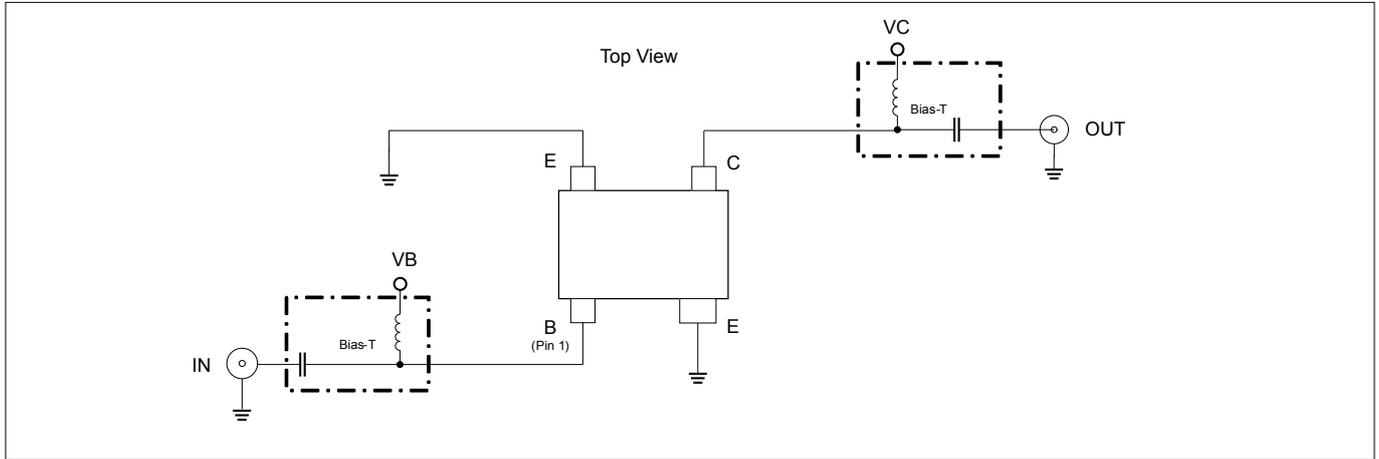


Figure 2 Testing circuit

Table 6 AC characteristics, $V_{CE} = 3\text{ V}$, $f = 150\text{ MHz}$

Parameter	Symbol	Values			Unit	Note or test condition
		Min.	Typ.	Max.		
Power gain		-		-	dB	$I_C = 90\text{ mA}$
<ul style="list-style-type: none"> Maximum power gain Transducer gain 	G_{ms} $ S_{21} ^2$		35.5 33.5			
Noise figure						$I_C = 50\text{ mA}$
<ul style="list-style-type: none"> Minimum noise figure Associated gain 	NF_{min} G_{ass}		1.55 32			
Linearity					dBm	$Z_S = Z_L = 50\text{ }\Omega$, $I_C = 90\text{ mA}$
<ul style="list-style-type: none"> 3rd order intercept point at output 1 dB gain compression point at output 	OIP_3 OP_{1dB}		30.5 19			

Table 7 AC characteristics, $V_{CE} = 3\text{ V}$, $f = 450\text{ MHz}$

Parameter	Symbol	Values			Unit	Note or test condition
		Min.	Typ.	Max.		
Power gain		-		-	dB	$I_C = 90\text{ mA}$
<ul style="list-style-type: none"> Maximum power gain Transducer gain 	G_{ms} $ S_{21} ^2$		29 25			
Noise figure						$I_C = 50\text{ mA}$
<ul style="list-style-type: none"> Minimum noise figure Associated gain 	NF_{min} G_{ass}		1.55 27.5			
Linearity					dBm	$Z_S = Z_L = 50\text{ }\Omega$, $I_C = 90\text{ mA}$
<ul style="list-style-type: none"> 3rd order intercept point at output 1 dB gain compression point at output 	OIP_3 OP_{1dB}		30 19			

Electrical characteristics
Table 8 AC characteristics, $V_{CE} = 3\text{ V}$, $f = 900\text{ MHz}$

Parameter	Symbol	Values			Unit	Note or test condition
		Min.	Typ.	Max.		
Power gain	G_{ms} $ S_{21} ^2$	–	23.5	–	dB	$I_C = 90\text{ mA}$
• Maximum power gain			19			
• Transducer gain						
Noise figure	NF_{min} G_{ass}		1.6		dBm	$I_C = 50\text{ mA}$
• Minimum noise figure			23			
• Associated gain						
Linearity	OIP_3 OP_{1dB}		30.5		dBm	$Z_S = Z_L = 50\ \Omega$, $I_C = 90\text{ mA}$
• 3rd order intercept point at output			19			
• 1 dB gain compression point at output						

Table 9 AC characteristics, $V_{CE} = 3\text{ V}$, $f = 1.5\text{ GHz}$

Parameter	Symbol	Values			Unit	Note or test condition
		Min.	Typ.	Max.		
Power gain	G_{ma} $ S_{21} ^2$	–	18	–	dB	$I_C = 90\text{ mA}$
• Maximum power gain			14			
• Transducer gain						
Noise figure	NF_{min} G_{ass}		1.65		dBm	$I_C = 50\text{ mA}$
• Minimum noise figure			17			
• Associated gain						
Linearity	OIP_3 OP_{1dB}		31		dBm	$Z_S = Z_L = 50\ \Omega$, $I_C = 90\text{ mA}$
• 3rd order intercept point at output			19			
• 1 dB gain compression point at output						

Table 10 AC characteristics, $V_{CE} = 3\text{ V}$, $f = 1.9\text{ GHz}$

Parameter	Symbol	Values			Unit	Note or test condition
		Min.	Typ.	Max.		
Power gain	G_{ma} $ S_{21} ^2$	–	15.5	–	dB	$I_C = 90\text{ mA}$
• Maximum power gain			11.5			
• Transducer gain						
Noise figure	NF_{min} G_{ass}		1.7		dBm	$I_C = 50\text{ mA}$
• Minimum noise figure			14			
• Associated gain						
Linearity	OIP_3 OP_{1dB}		31		dBm	$Z_S = Z_L = 50\ \Omega$, $I_C = 90\text{ mA}$
• 3rd order intercept point at output			19			
• 1 dB gain compression point at output						

Electrical characteristics
Table 11 AC characteristics, $V_{CE} = 3\text{ V}$, $f = 2.4\text{ GHz}$

Parameter	Symbol	Values			Unit	Note or test condition
		Min.	Typ.	Max.		
Power gain	G_{ma} $ S_{21} ^2$	–	13.5	–	dB	$I_C = 90\text{ mA}$
<ul style="list-style-type: none"> Maximum power gain Transducer gain 			9.5			
Noise figure	NF_{min} G_{ass}		1.8			$I_C = 50\text{ mA}$
<ul style="list-style-type: none"> Minimum noise figure Associated gain 			12			
Linearity	OIP_3 OP_{1dB}		30		dBm	$Z_S = Z_L = 50\ \Omega$, $I_C = 90\text{ mA}$
<ul style="list-style-type: none"> 3rd order intercept point at output 1 dB gain compression point at output 			19			

Table 12 AC characteristics, $V_{CE} = 3\text{ V}$, $f = 3.5\text{ GHz}$

Parameter	Symbol	Values			Unit	Note or test condition
		Min.	Typ.	Max.		
Power gain	G_{ma} $ S_{21} ^2$	–	10	–	dB	$I_C = 90\text{ mA}$
<ul style="list-style-type: none"> Maximum power gain Transducer gain 			6			
Noise figure	NF_{min} G_{ass}		2.05			$I_C = 50\text{ mA}$
<ul style="list-style-type: none"> Minimum noise figure Associated gain 			9			
Linearity	OIP_3 OP_{1dB}		29.5		dBm	$Z_S = Z_L = 50\ \Omega$, $I_C = 90\text{ mA}$
<ul style="list-style-type: none"> 3rd order intercept point at output 1 dB gain compression point at output 			18.5			

Note: $G_{ms} = |S_{21} / S_{12}|$ for $k < 1$; $G_{ma} = |S_{21} / S_{12}| (k - (k^2 - 1)^{1/2})$ for $k > 1$. In order to get the NF_{min} values stated in this chapter, the test fixture losses have been subtracted from all measured results. OIP_3 value depends on termination of all intermodulation frequency components. Termination used for this measurement is $50\ \Omega$ from 0.1 MHz to 6 GHz.

Electrical characteristics

3.4 Characteristic DC diagrams

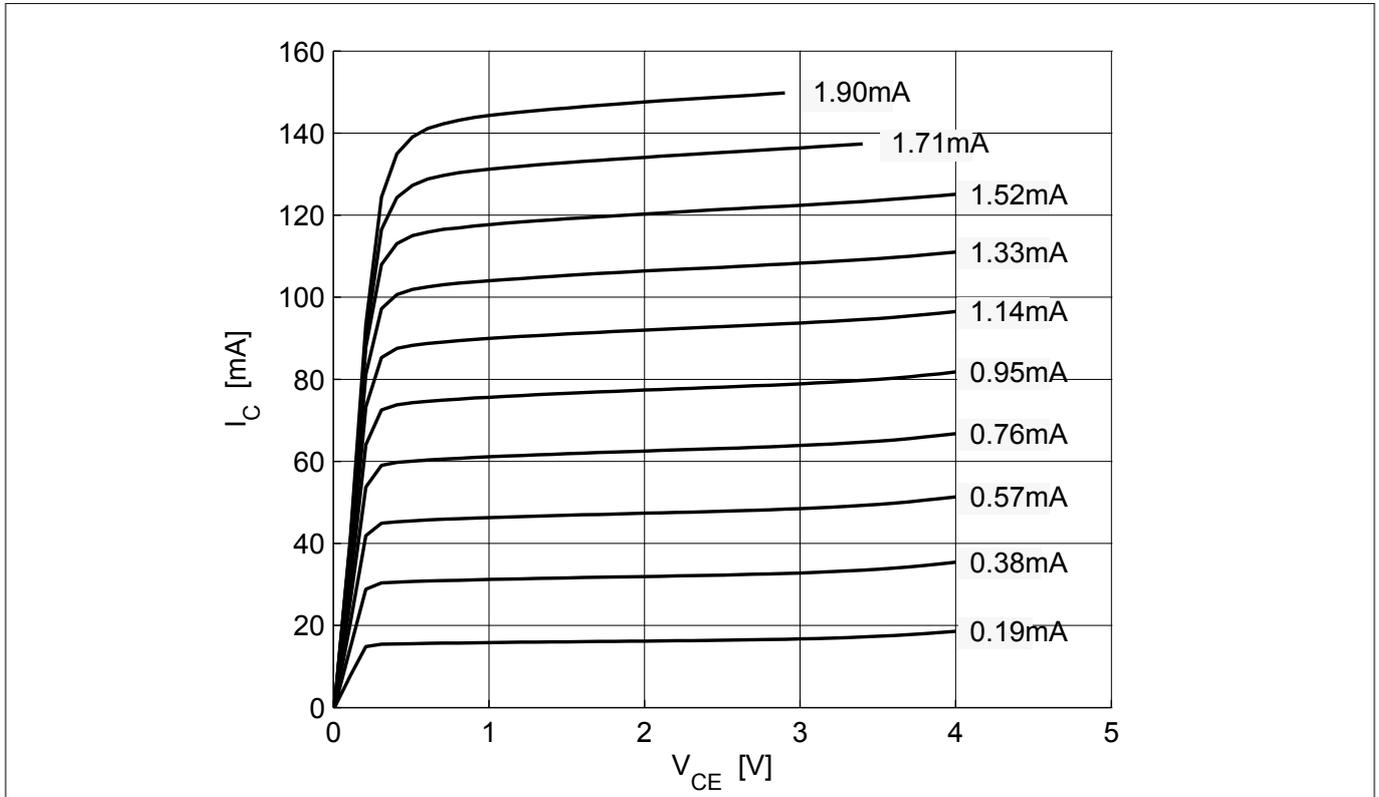


Figure 3 Collector current vs. collector emitter voltage $I_C = f(V_{CE}), I_B = \text{parameter}$

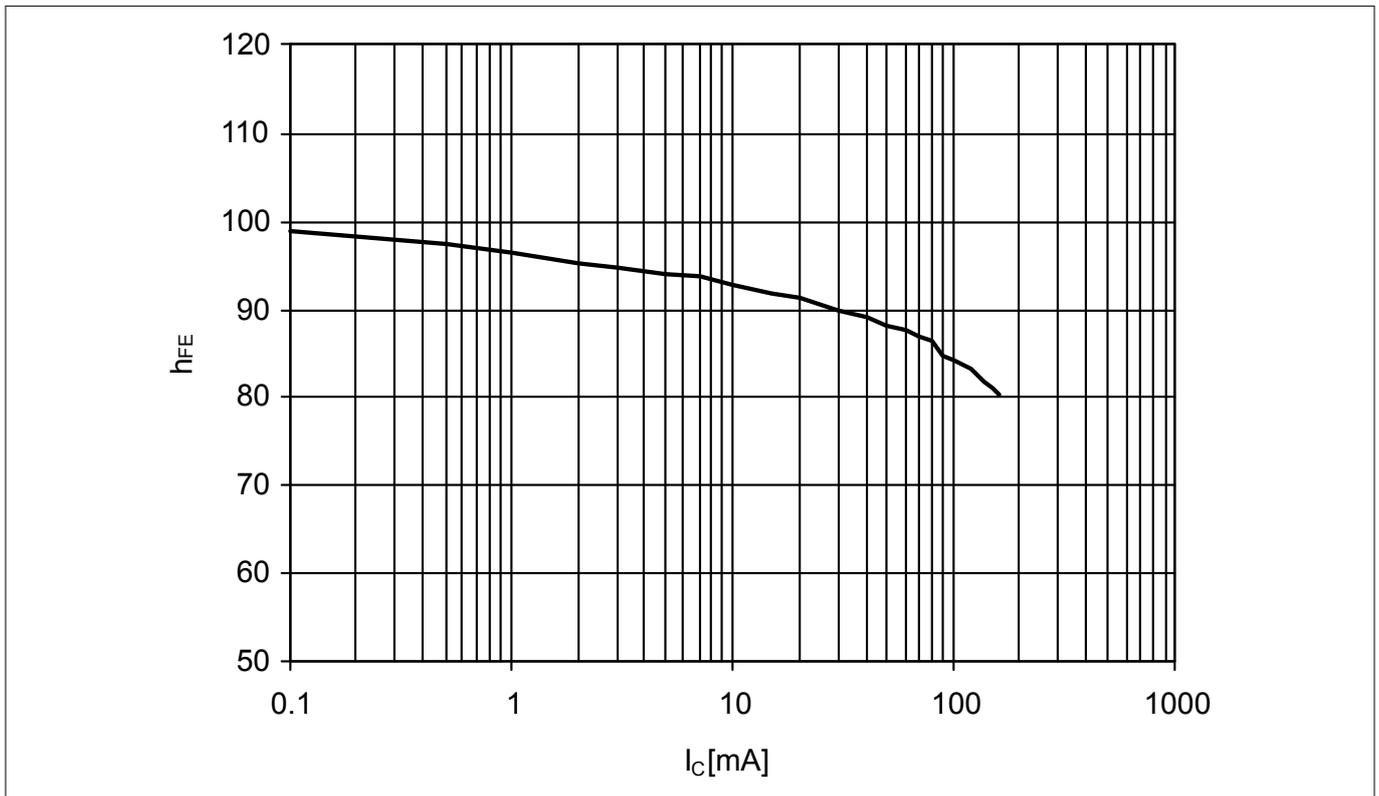


Figure 4 DC current gain $h_{FE} = f(I_C), V_{CE} = 3 \text{ V}$

Electrical characteristics

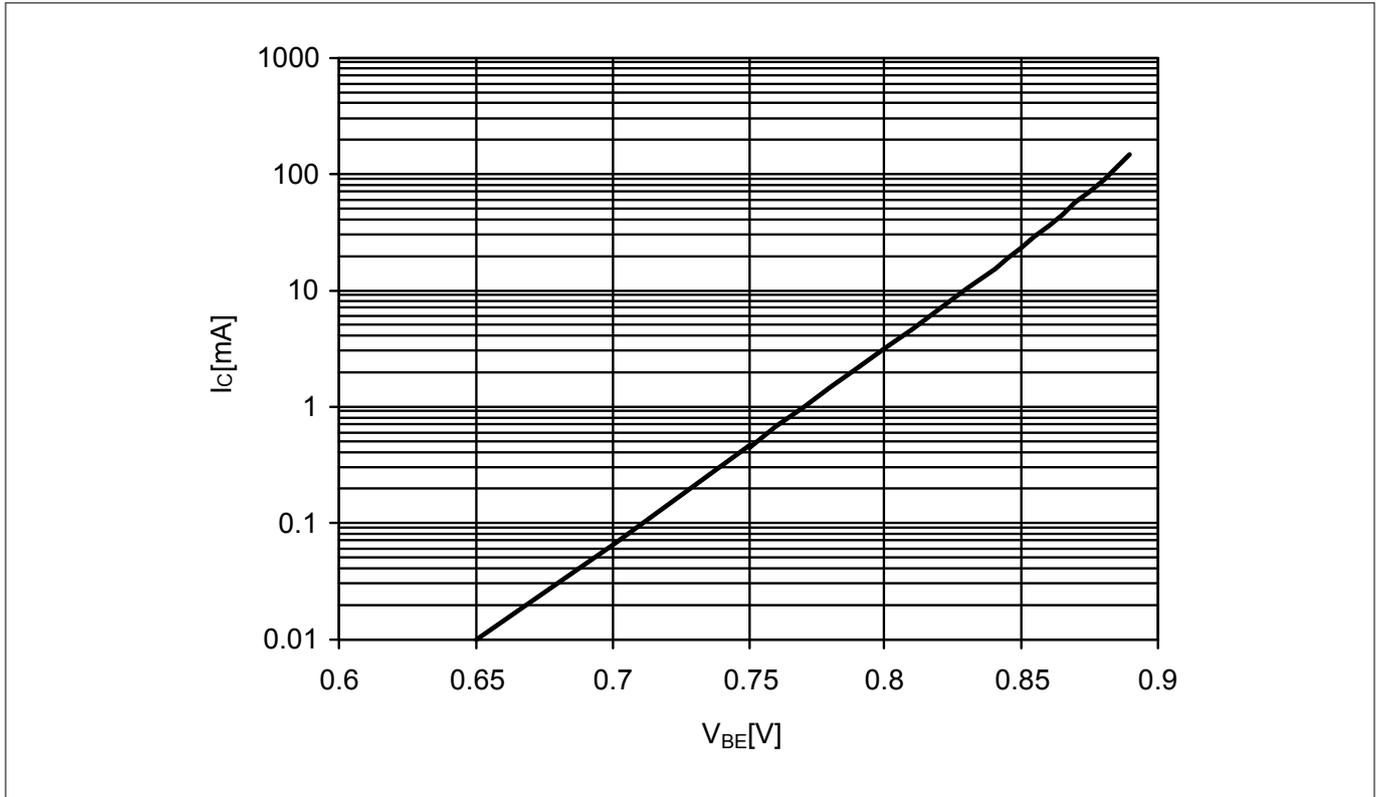


Figure 5 Collector current vs. base emitter forward voltage $I_C = f(V_{BE})$, $V_{CE} = 2\text{ V}$

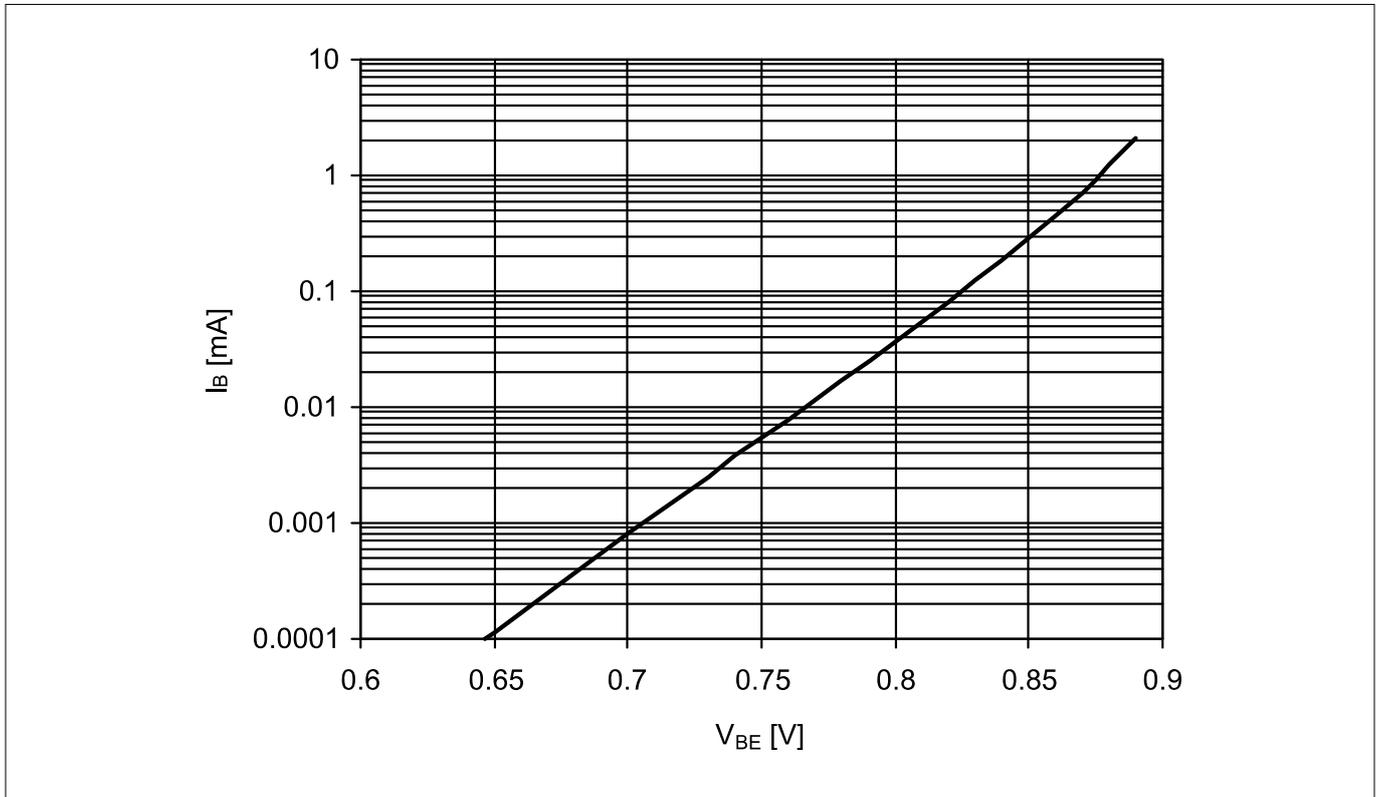


Figure 6 Base current vs. base emitter forward voltage $I_B = f(V_{BE})$, $V_{CE} = 2\text{ V}$

Electrical characteristics

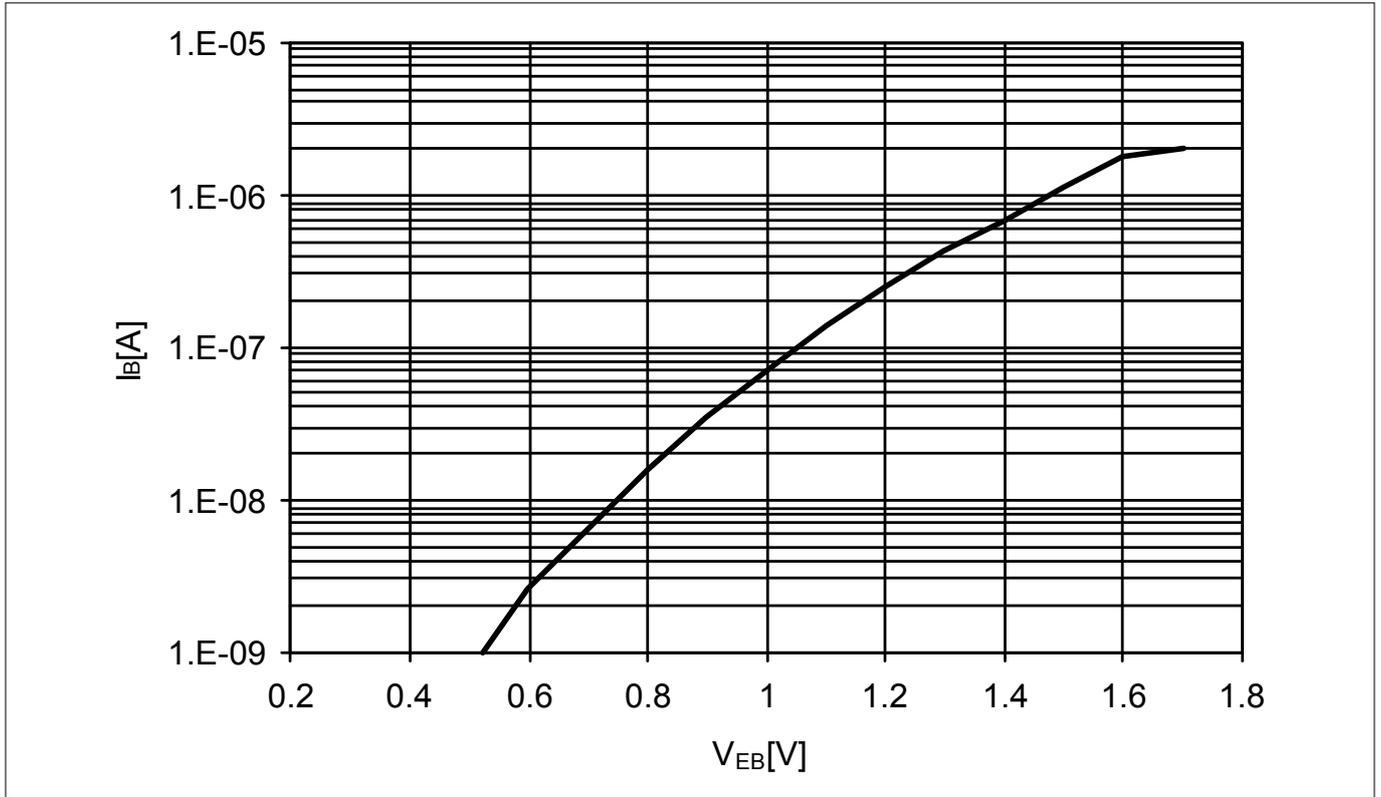


Figure 7 Base current vs. base emitter reverse voltage $I_B = f(V_{EB}), V_{CE} = 2\text{ V}$

Electrical characteristics

3.5 Characteristic AC diagrams

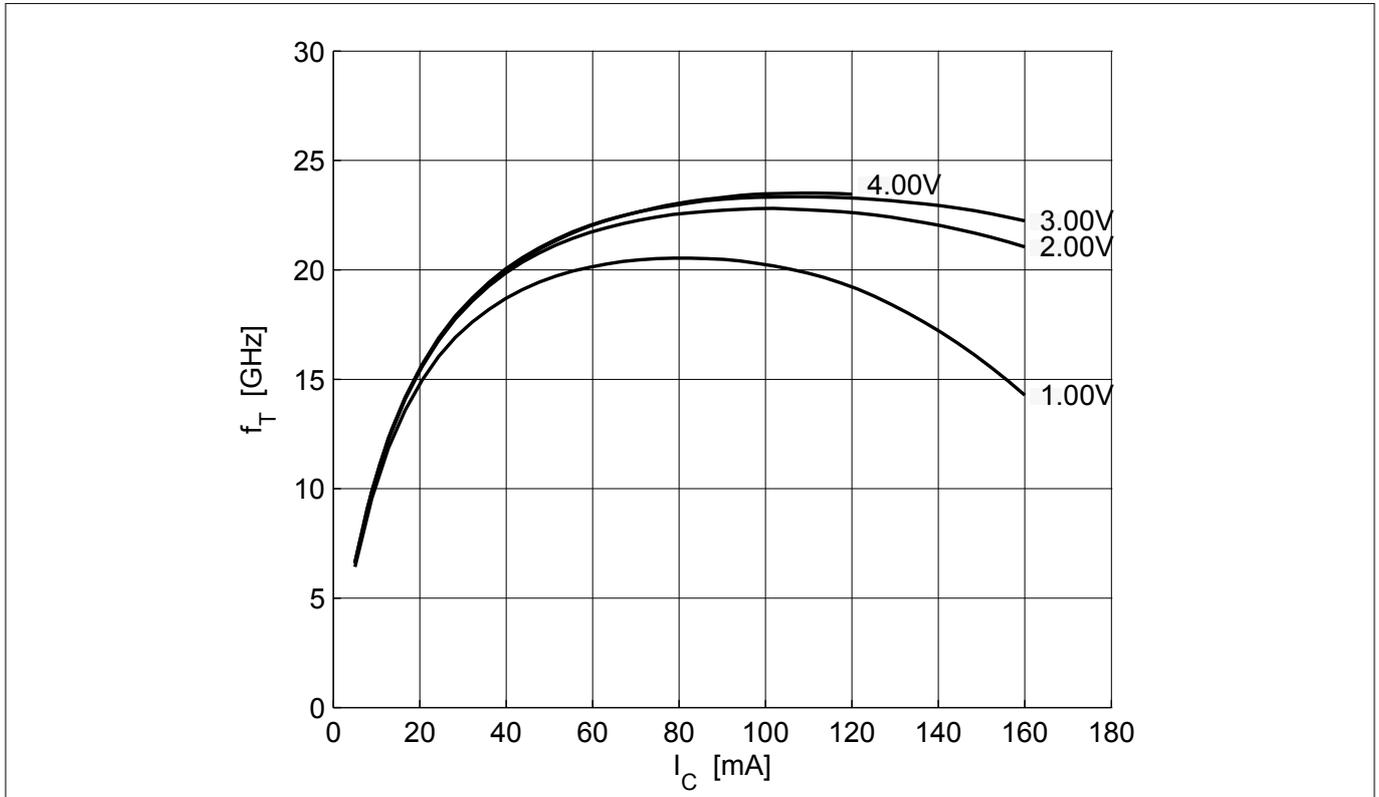


Figure 8 Transition frequency $f_T = f(I_C)$, $f = 1 \text{ GHz}$, $V_{CE} = \text{parameter}$

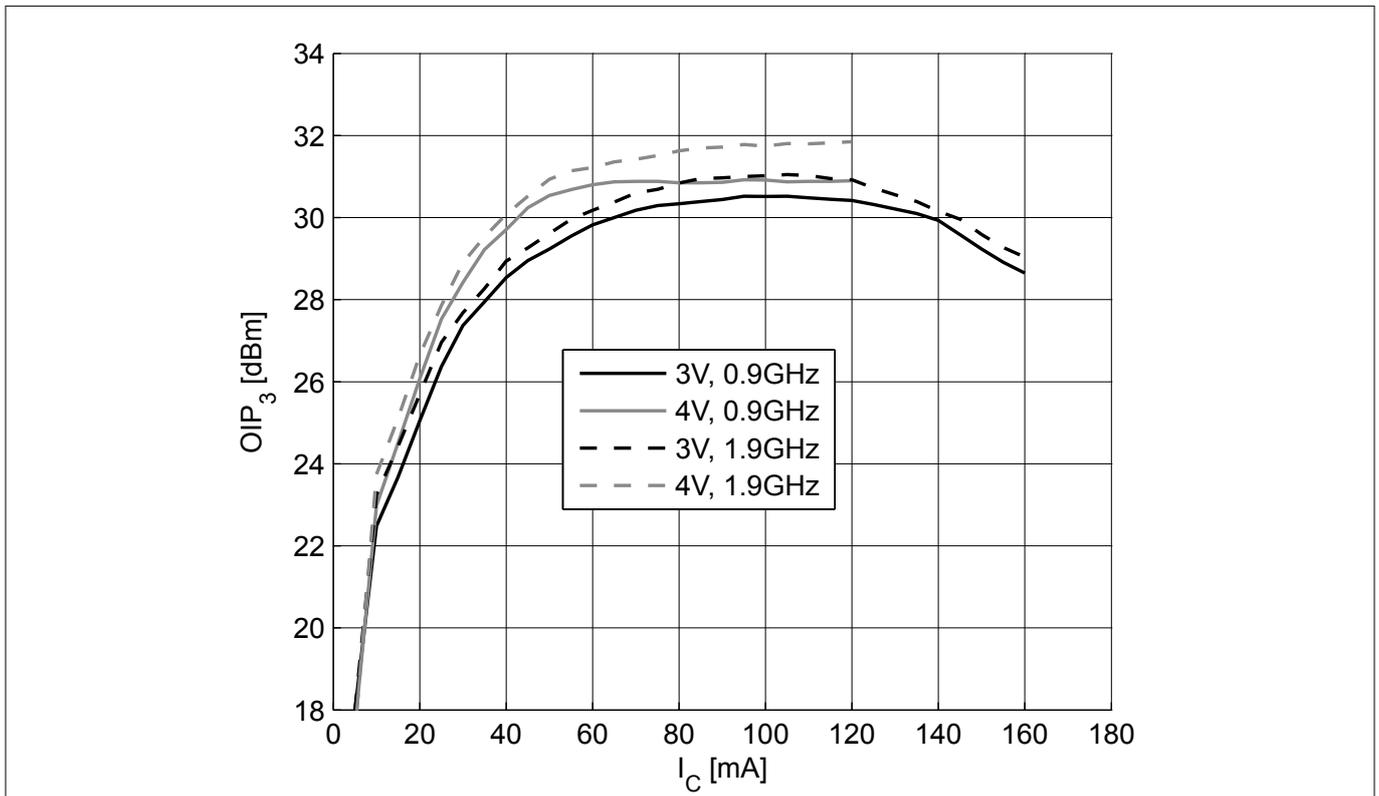


Figure 9 3rd order intercept point $OIP_3 = f(I_C)$, $Z_S = Z_L = 50 \Omega$, V_{CE} , $f = \text{parameters}$

Electrical characteristics

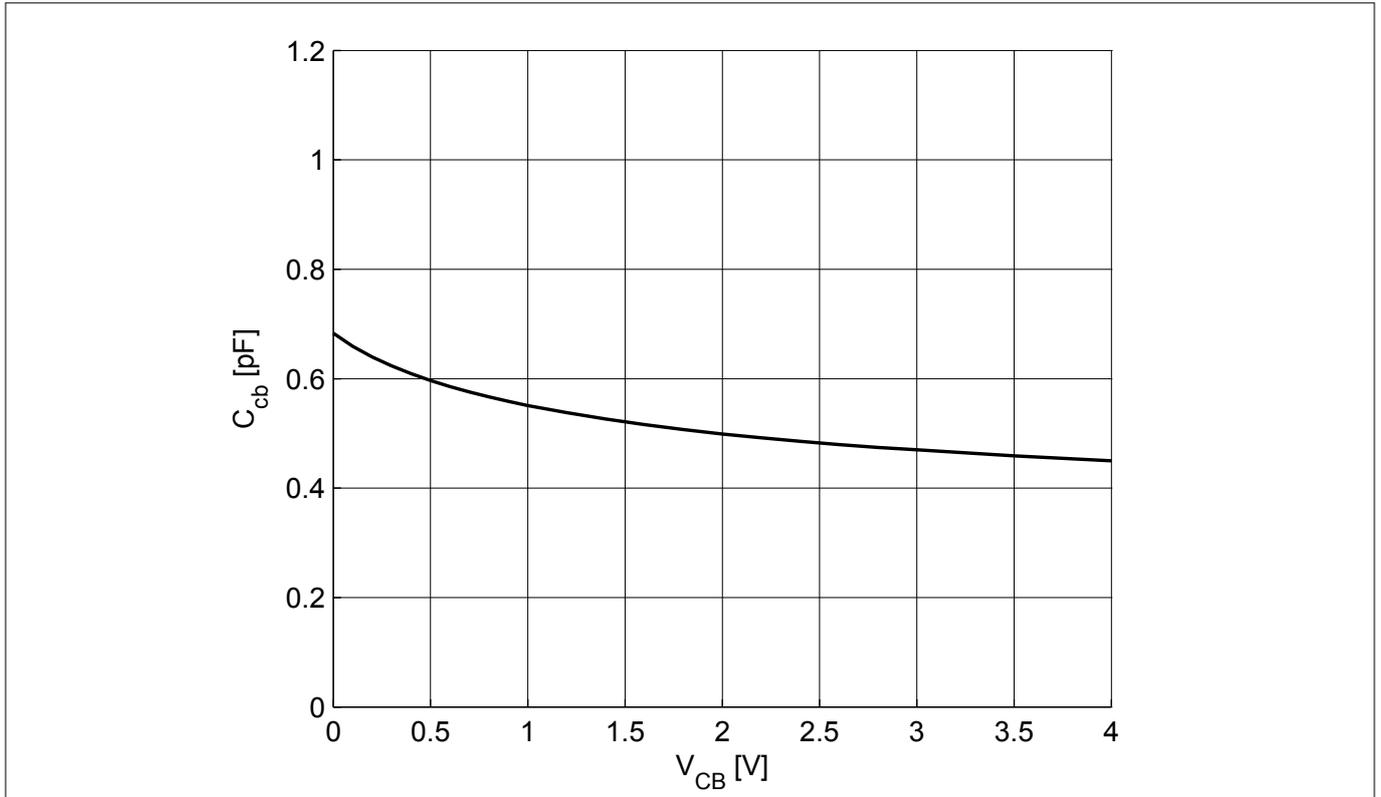


Figure 10 Collector base capacitance $C_{CB} = f(V_{CB}), f = 1 \text{ MHz}$

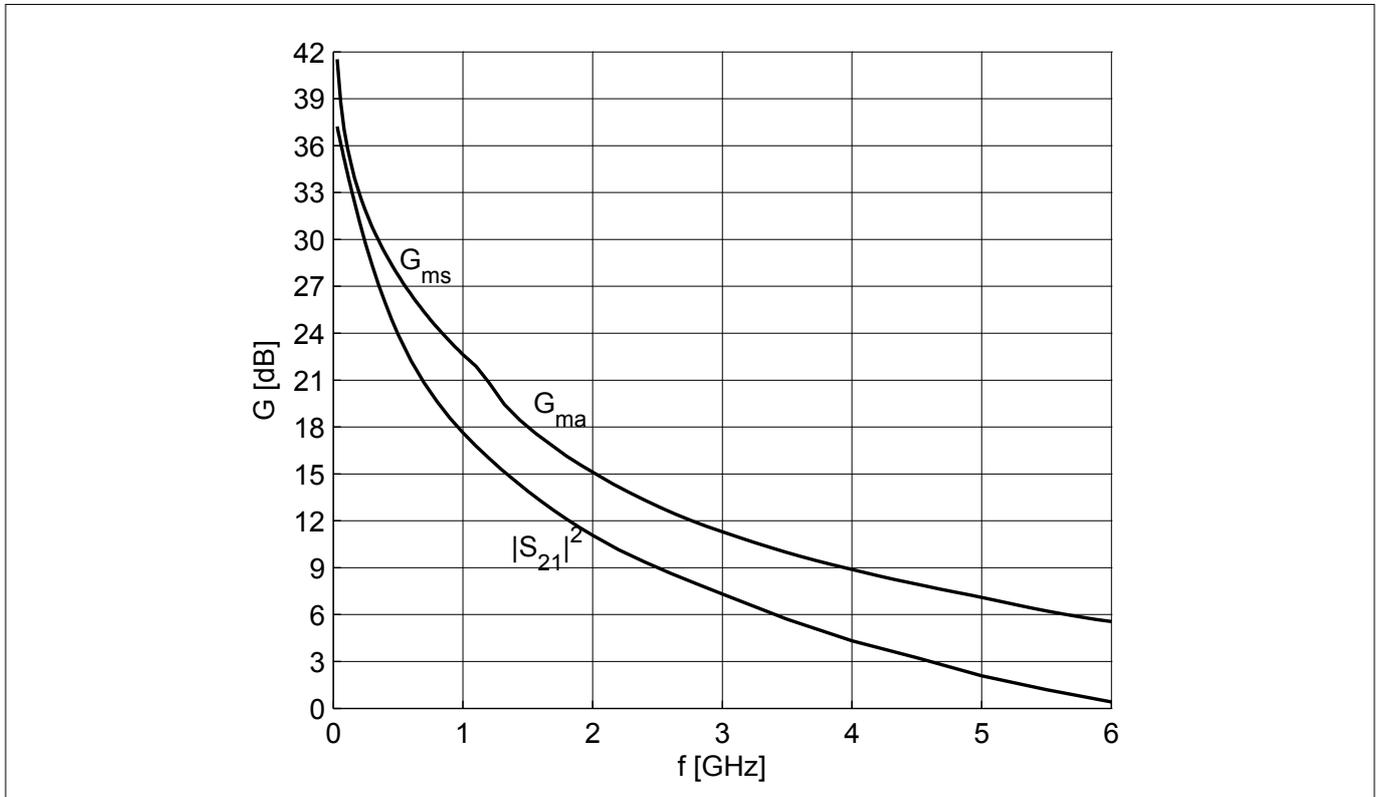


Figure 11 Gain $G_{ma}, G_{ms}, |S_{21}|^2 = f(f), V_{CE} = 3 \text{ V}, I_C = 90 \text{ mA}$

Electrical characteristics

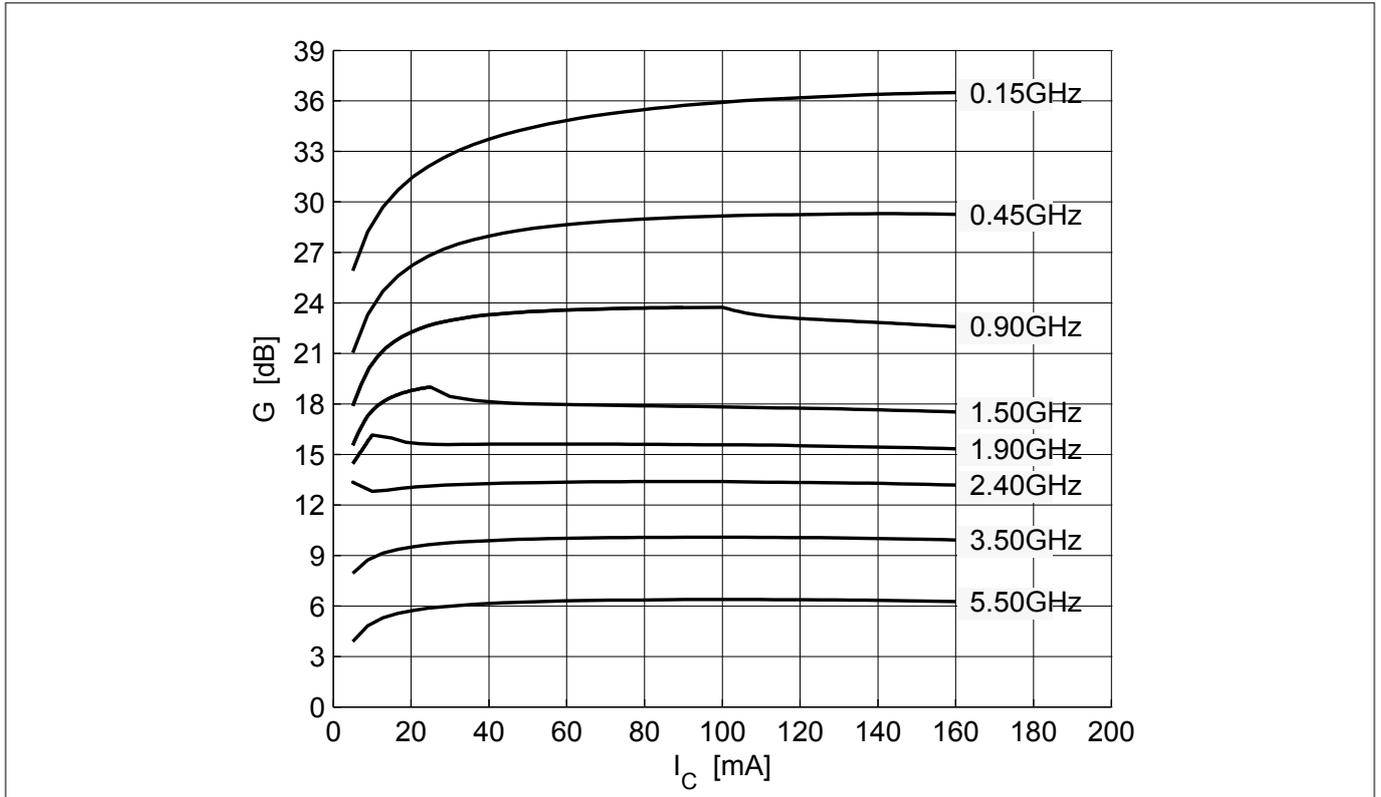


Figure 12 Maximum power gain $G_{max} = f(I_C)$, $V_{CE} = 3\text{ V}$, $f = \text{parameter in GHz}$

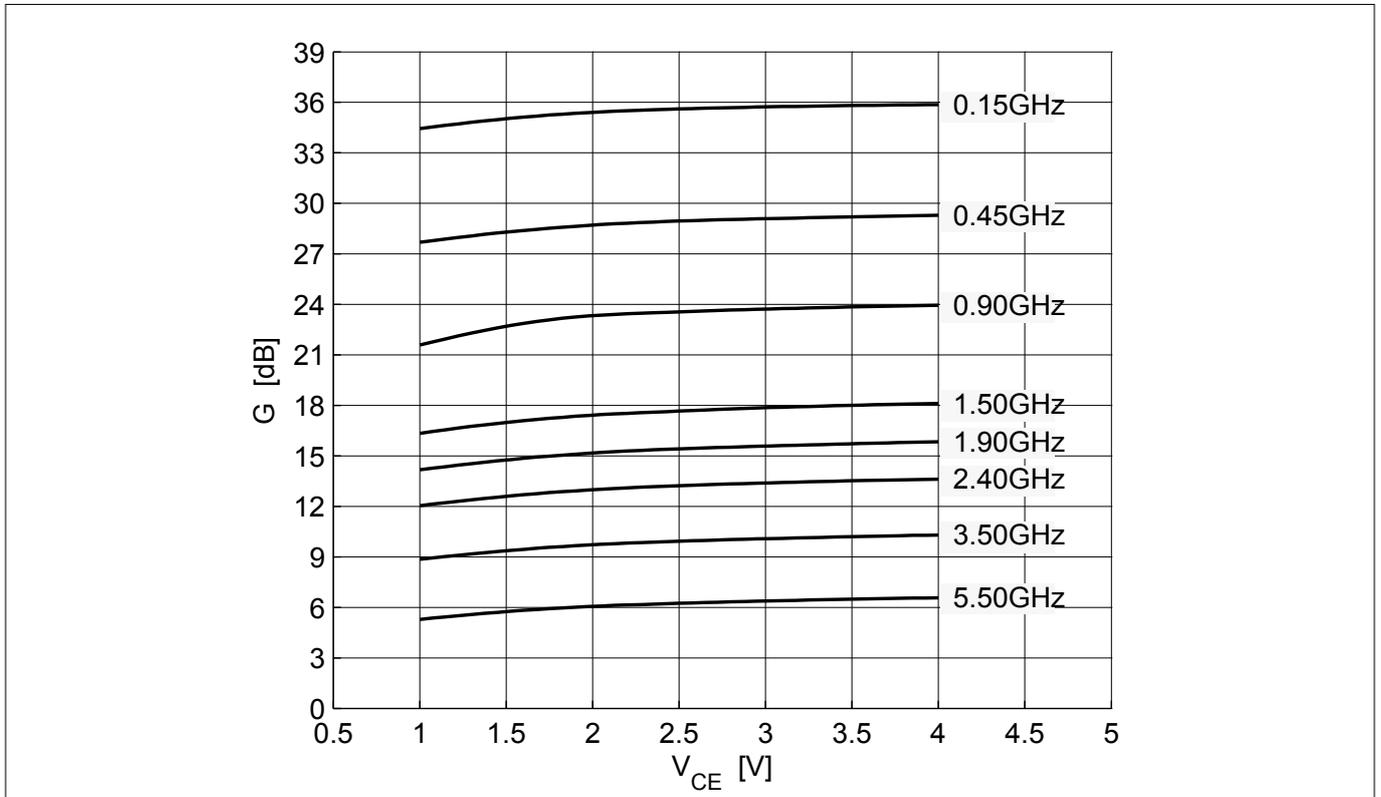


Figure 13 Maximum power gain $G_{max} = f(V_{CE})$, $I_C = 90\text{ mA}$, $f = \text{parameter in GHz}$

Electrical characteristics

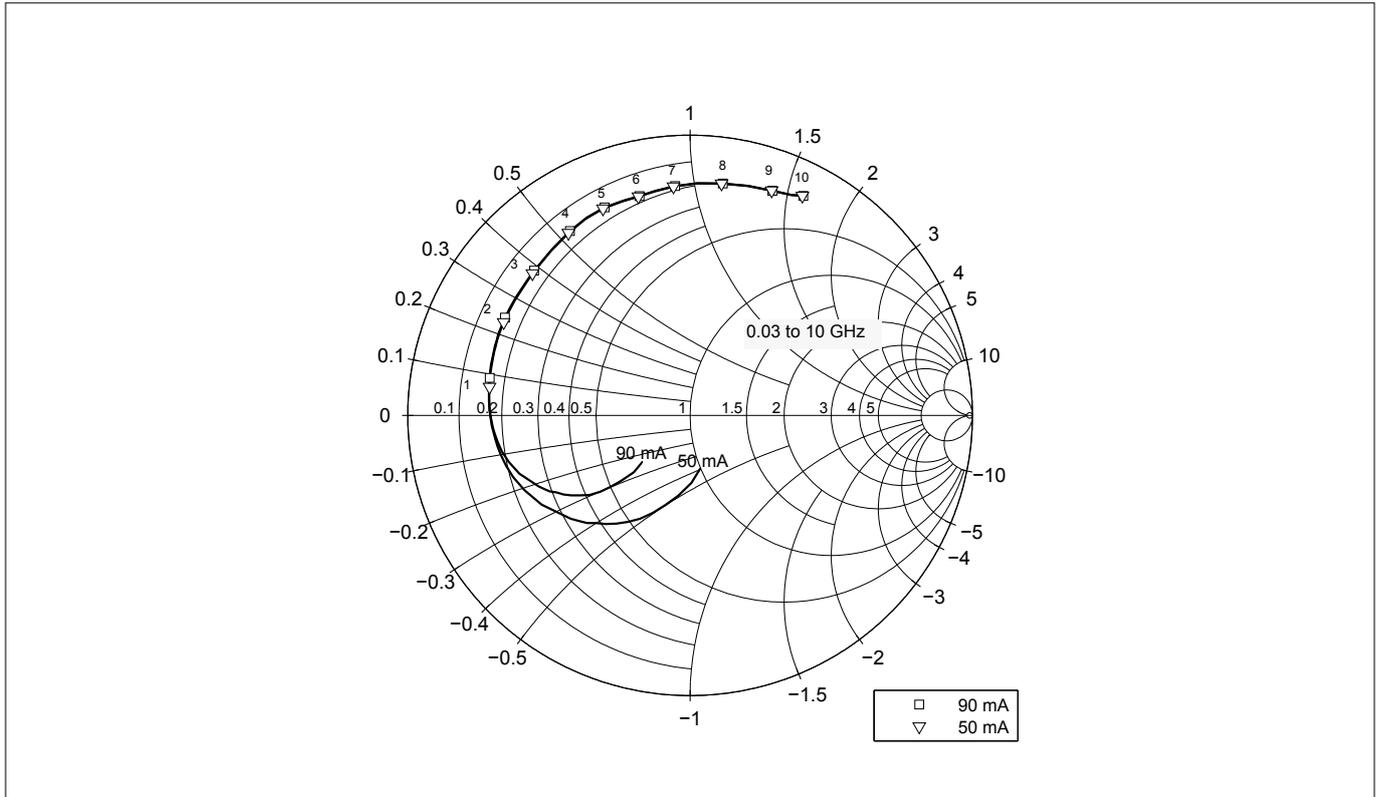


Figure 14 Input reflection coefficient $S_{11} = f(f)$, $V_{CE} = 3V$, $I_C = 50 / 90mA$

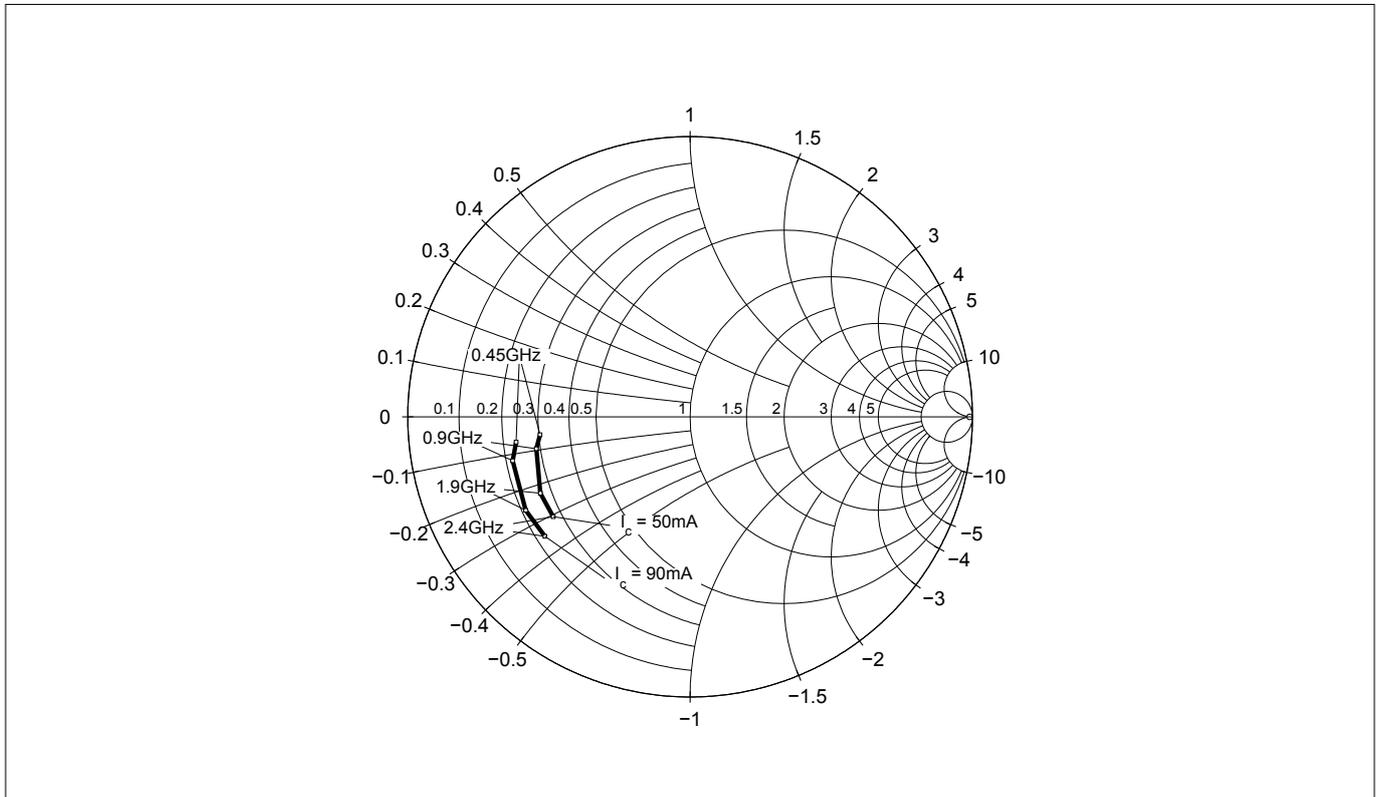


Figure 15 Source impedance for minimum noise figure $Z_{S,opt} = f(f)$, $V_{CE} = 3V$, $I_C = 50 / 90mA$

Electrical characteristics

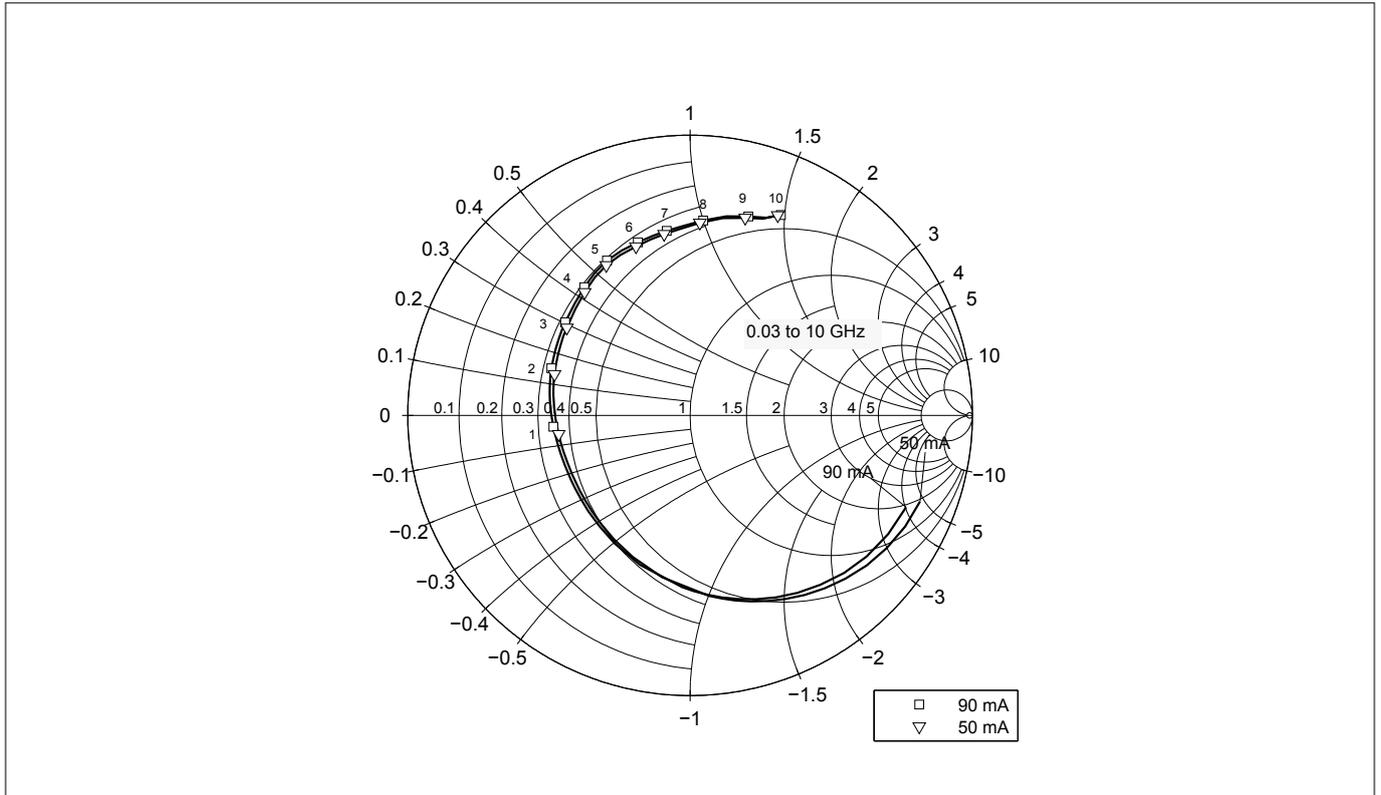


Figure 16 Output reflection coefficient $S_{22} = f(f)$, $V_{CE} = 3\text{ V}$, $I_C = 50 / 90\text{ mA}$

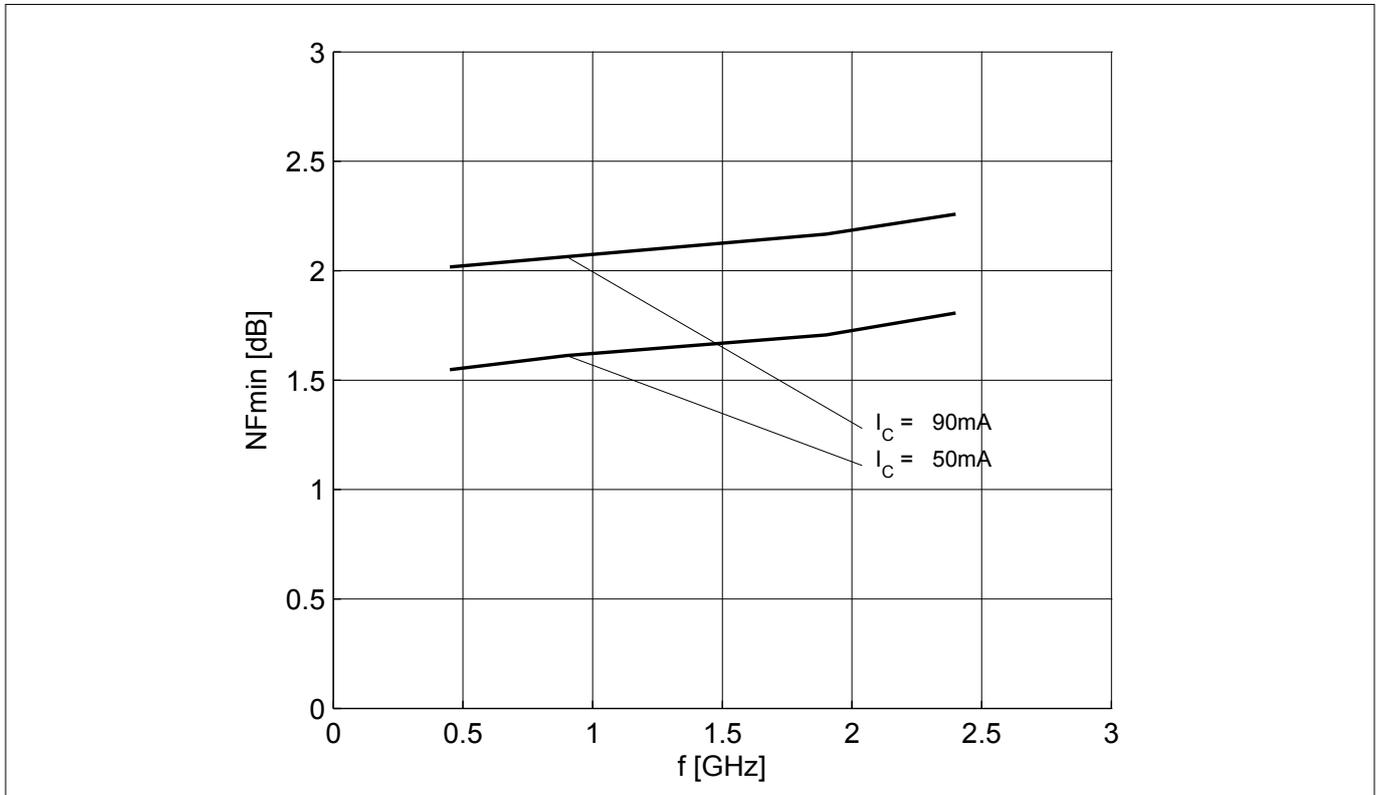


Figure 17 Noise figure $NF_{min} = f(f)$, $Z_S = Z_{S,opt}$, $V_{CE} = 3\text{ V}$, $I_C = 50 / 90\text{ mA}$

Electrical characteristics

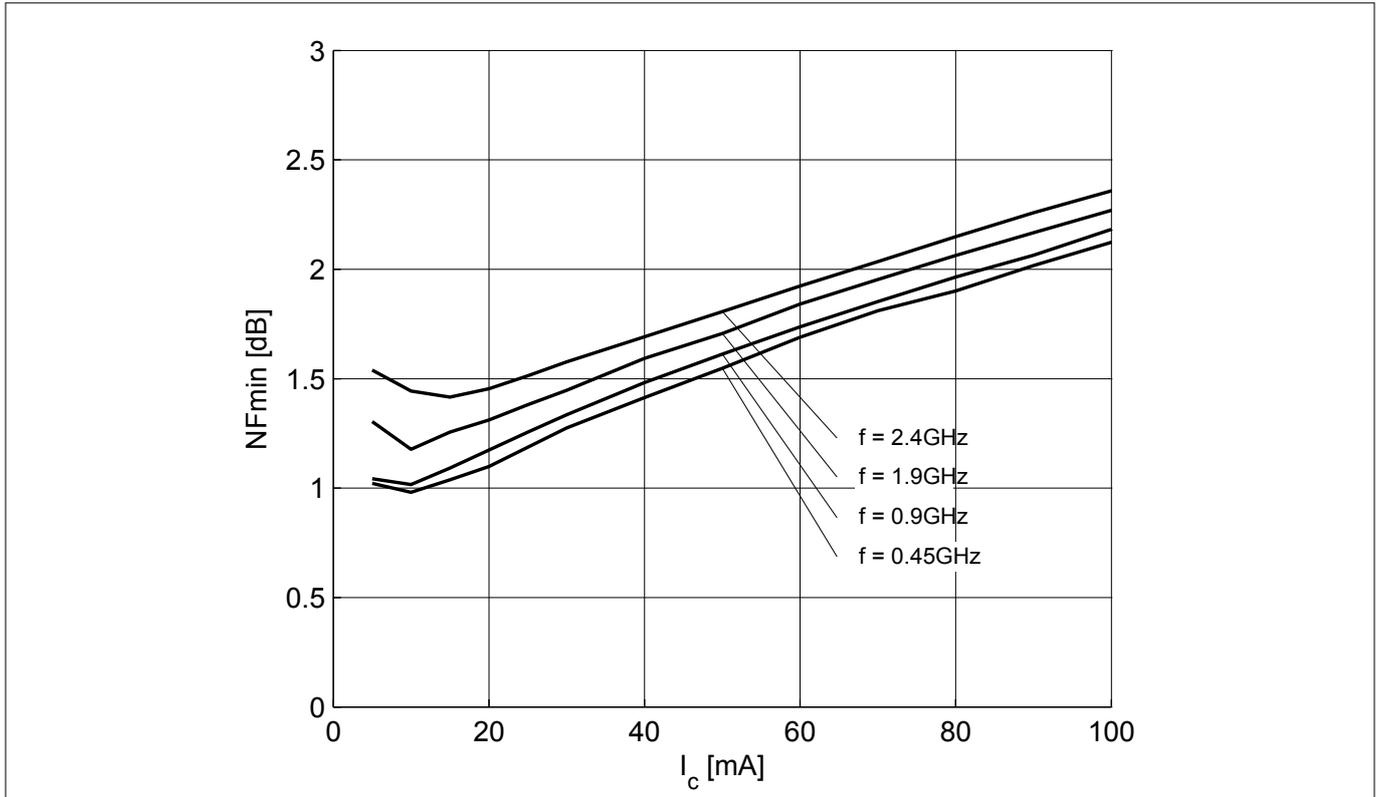


Figure 18 Noise figure $NF_{min} = f(I_C), Z_S = Z_{S,opt}, V_{CE} = 3 V, f = \text{parameter in GHz}$

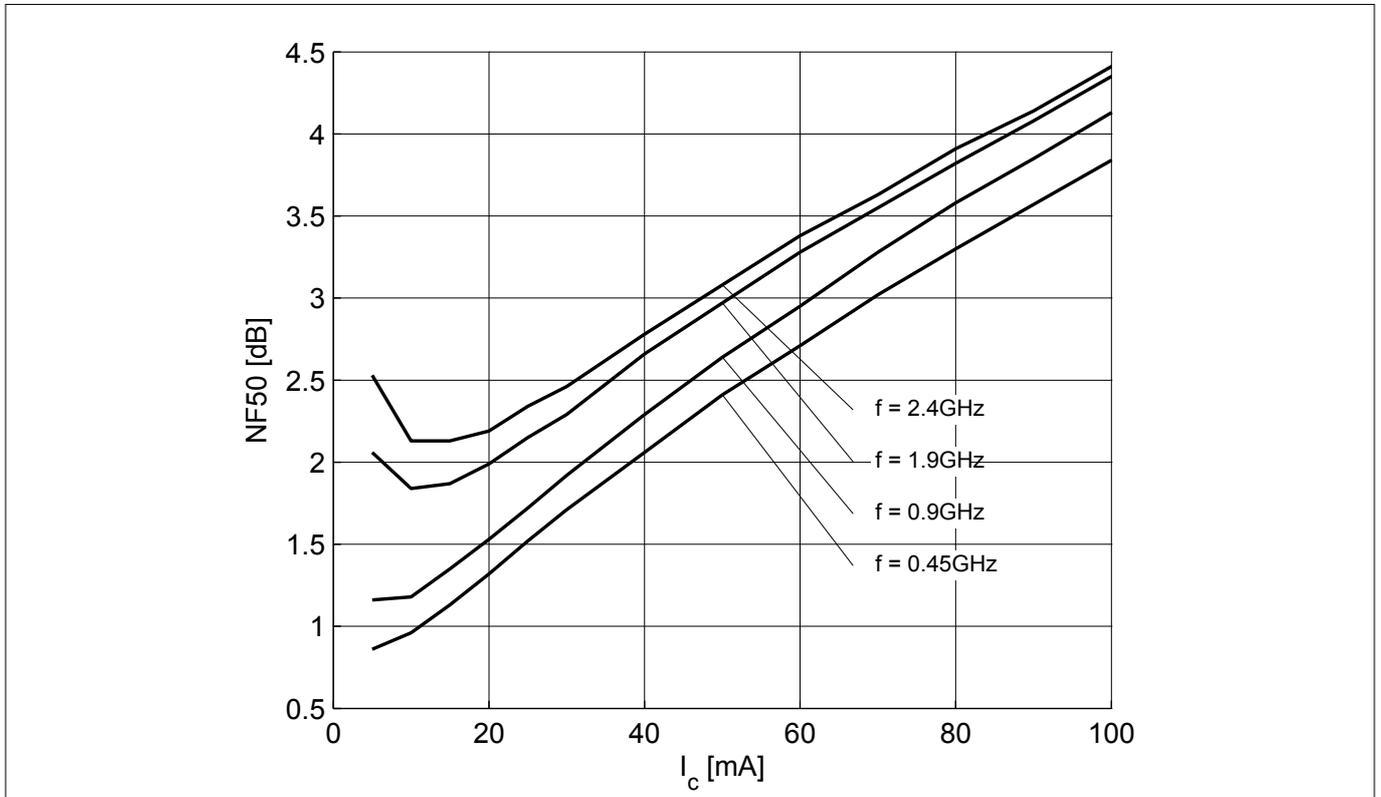


Figure 19 Noise figure $NF_{50} = f(I_C), Z_S = 50 \Omega, V_{CE} = 3 V, f = \text{parameter in GHz}$

Electrical characteristics

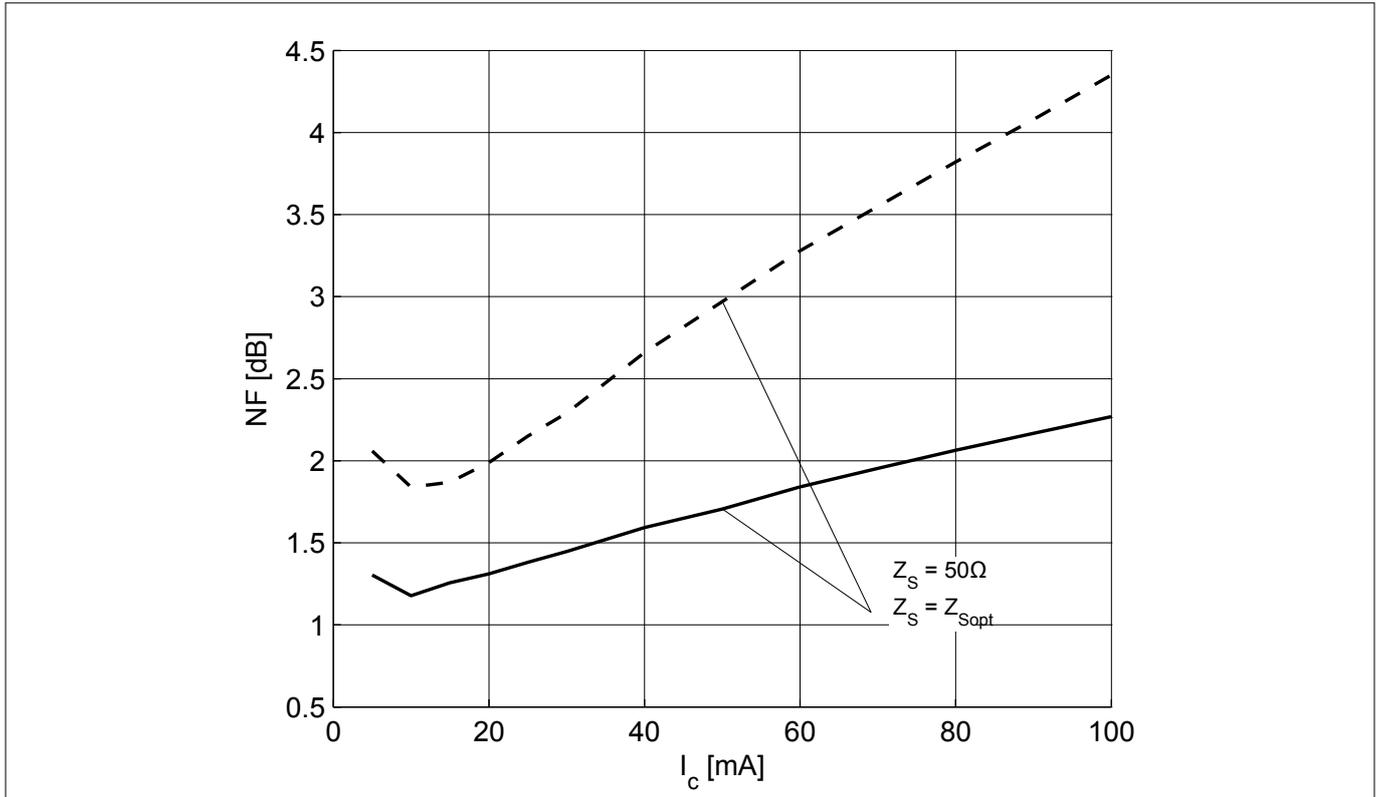


Figure 20 Noise figure $NF_{50} = f(I_C)$, $Z_S = 50 \Omega$, $NF_{min} = f(I_C)$, $Z_S = Z_{S,opt}$, $V_{CE} = 3 V$, $f = 1.9 GHz$

Note: The curves shown in this chapter have been generated using typical devices but shall not be considered as a guarantee that all devices have identical characteristic curves. $T_A = 25 \text{ }^\circ\text{C}$.

Package information SOT343

4 Package information SOT343

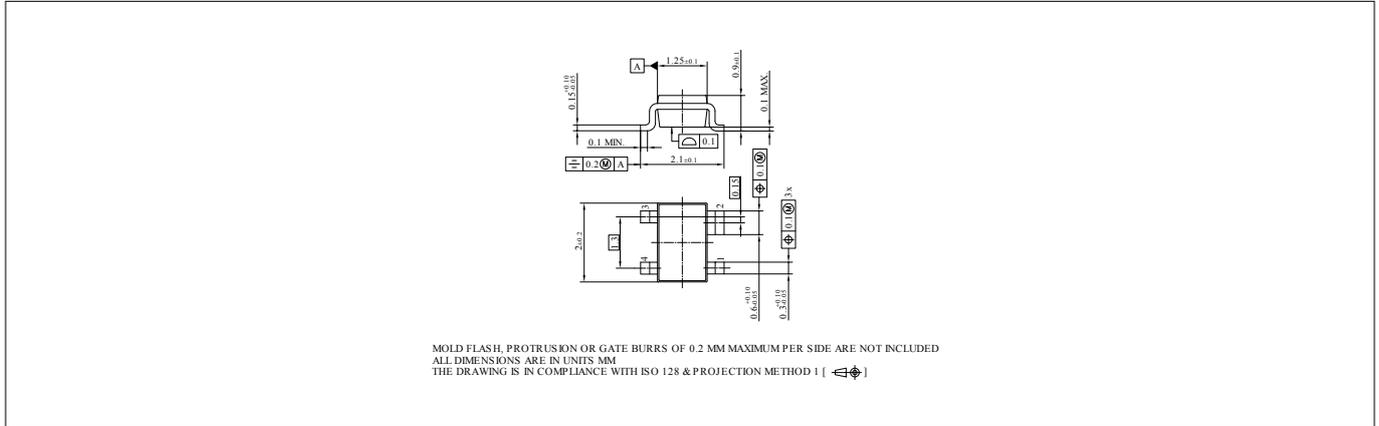


Figure 21 Package outline

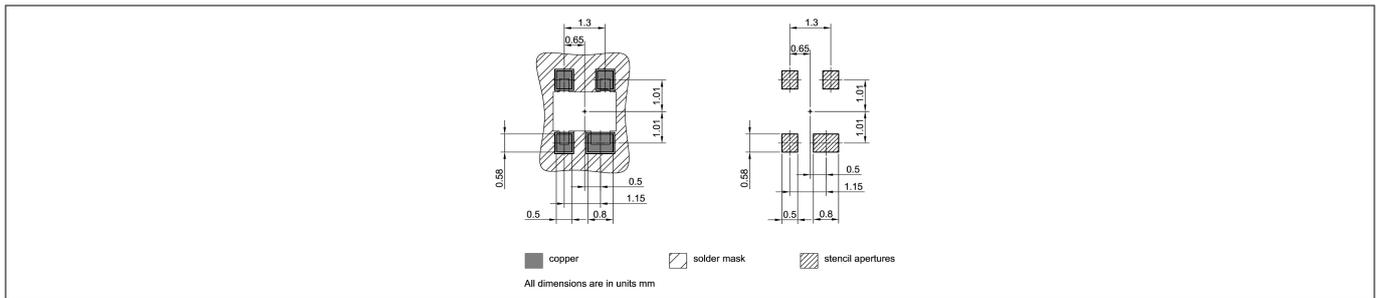


Figure 22 Foot print

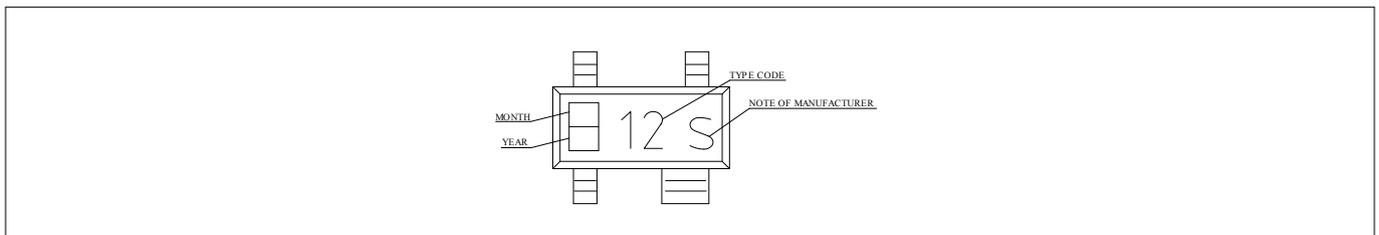


Figure 23 Marking layout example

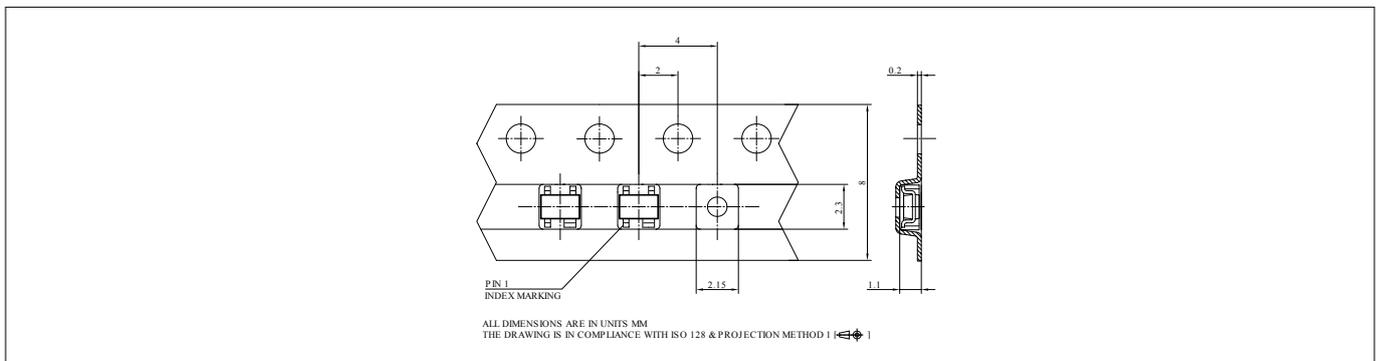


Figure 24 Tape dimensions

Revision history**Revision history**

Document version	Date of release	Description of changes
Revision 2.0	2019-01-25	New datasheet layout.

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